

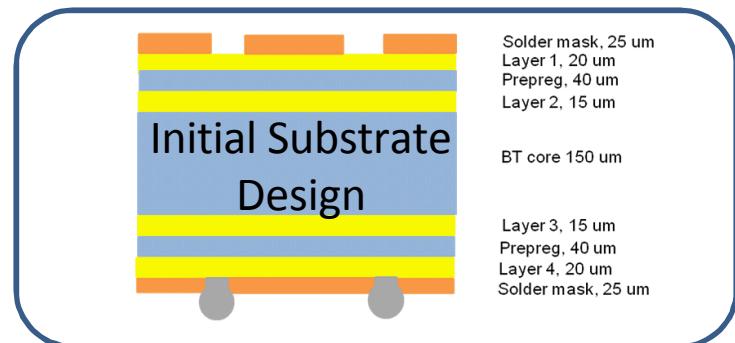
Optical Deformation Chamber using Digital Image Correlation (DIC)

**Jon-Claude Leger, Nathan Young,
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23rd Annual Rio Grande Symposium on Advanced Materials
Hotel Albuquerque
October 3, 2011

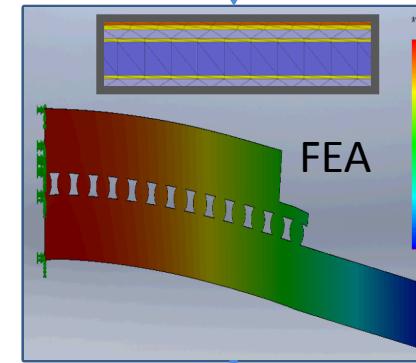
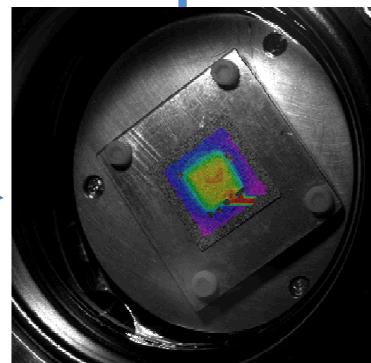
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Motivation

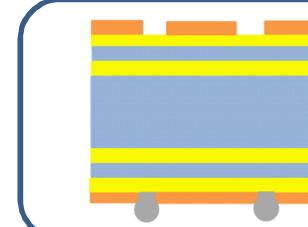


A system was developed to perform experiments which can measure the deformation microsystems components to validate structural models.

Simulation Based Design

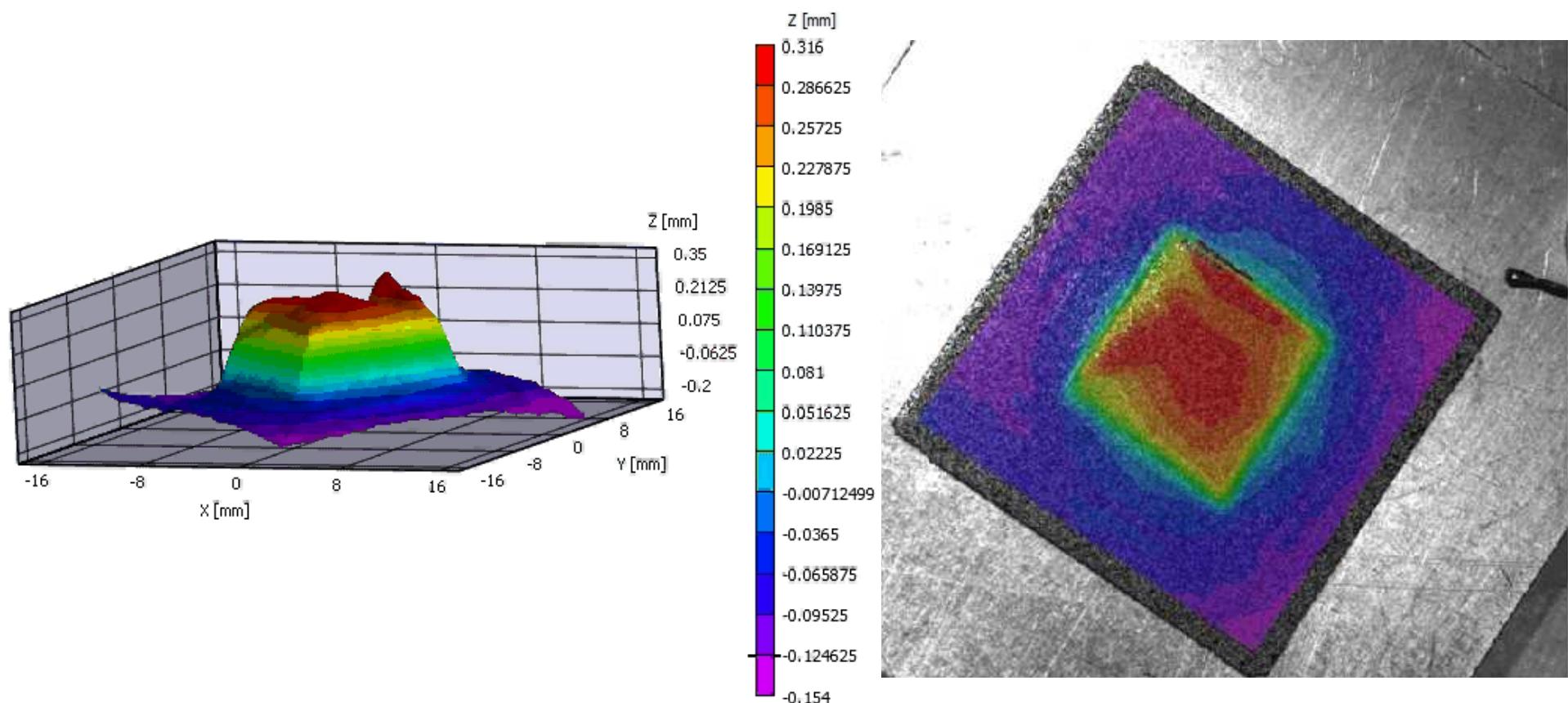


The focus of this work was developing a means of validating structural microsystems models. The data from this experiment can be used to gain trust in the model which can then be used to identify better designs.





Full 3D and 2D Characterization



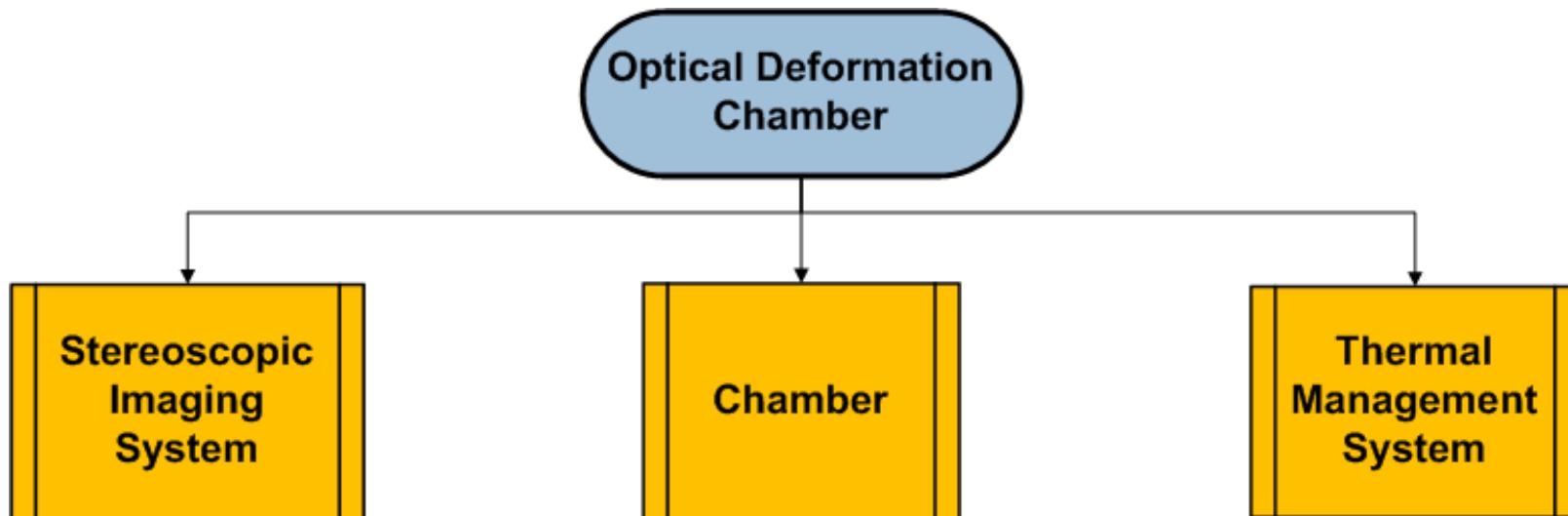


Outline

- **Optical Deformation Chamber Setup**
 - Chamber Design
 - Temperature Cycling System
 - Machine Vision Components
- **DIC Method**
 - Calibration
 - Image Acquisition
 - Analysis
- **Device Testing**
 - Thermal Verification
 - Deformation and Strain Analysis
- **Concluding Remarks**



Optical Deformation Chamber



Controlled imaging environment
-Eliminate external lighting variation
-Minimize internally reflected light
-Uniform illumination

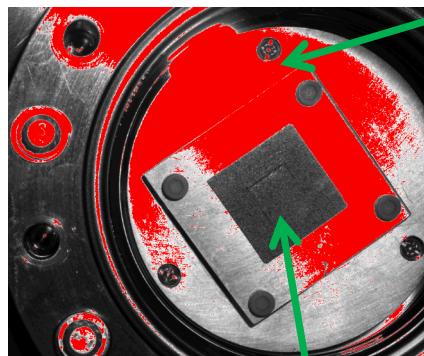
Flexible and easy device setup

-55°C to 125 °C
Device Temp



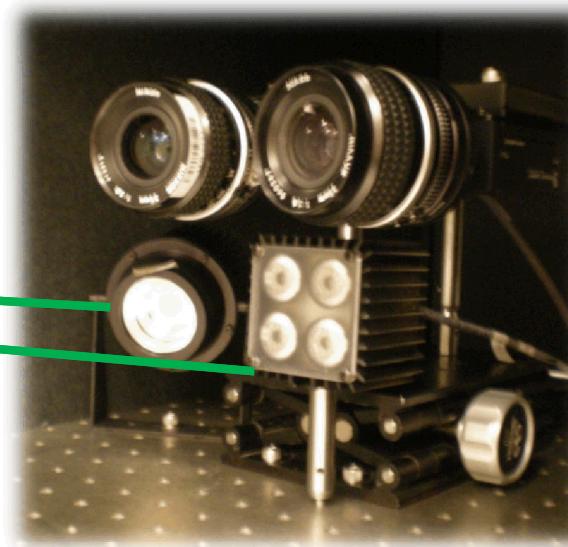
Machine Vision System

Lighting



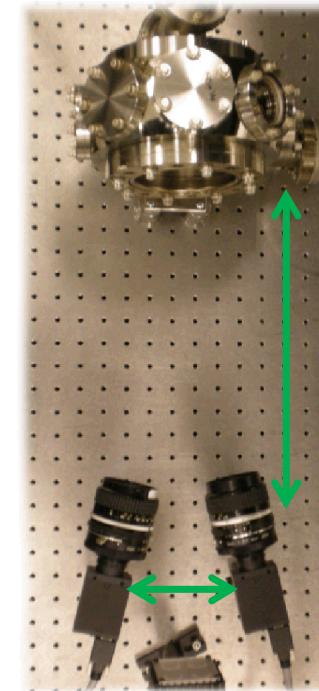
Diffuse

Lighting selection, minimizing reflections and eliminating external lighting enhance image quality.



Multiple White LED light sources

Stereoscopic Cameras



Extrinsic parameters define camera orientation.

Imaging Software

Vic3D from Correlated Solutions was selected due to its simplicity and ease of use.

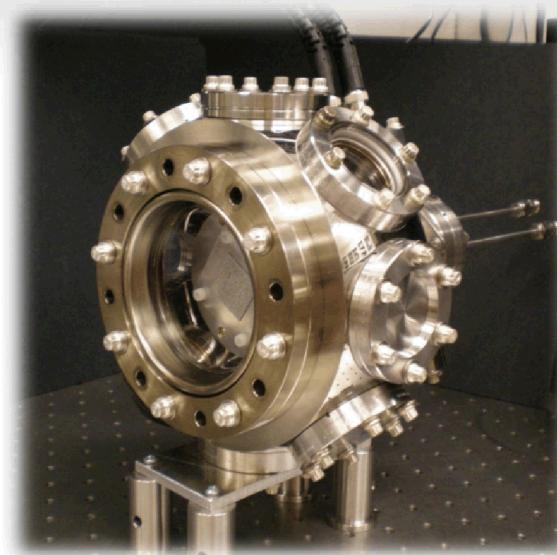
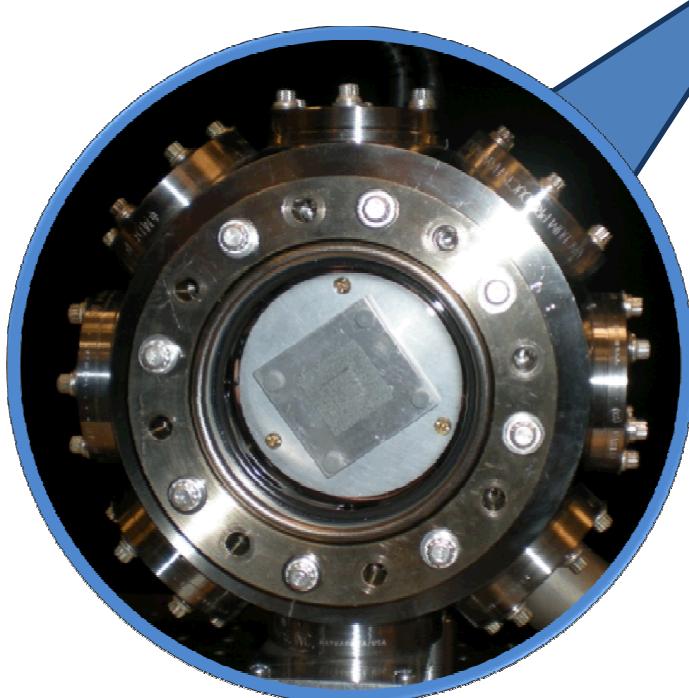
Intrinsic parameters define image point to camera reference frame.



Chamber Design

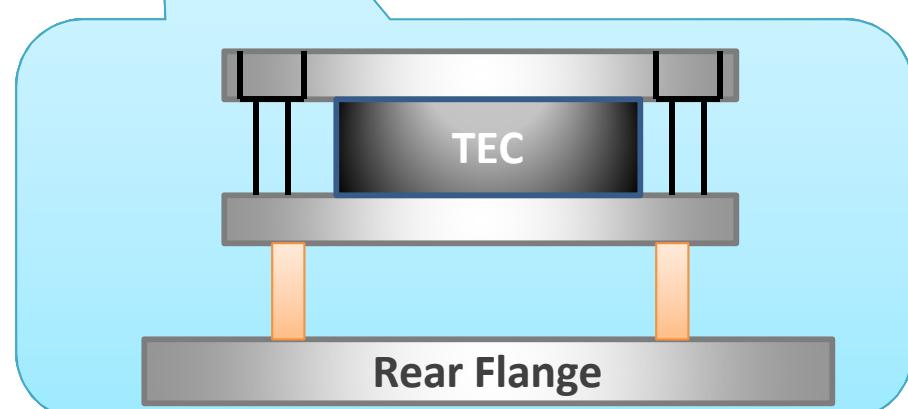
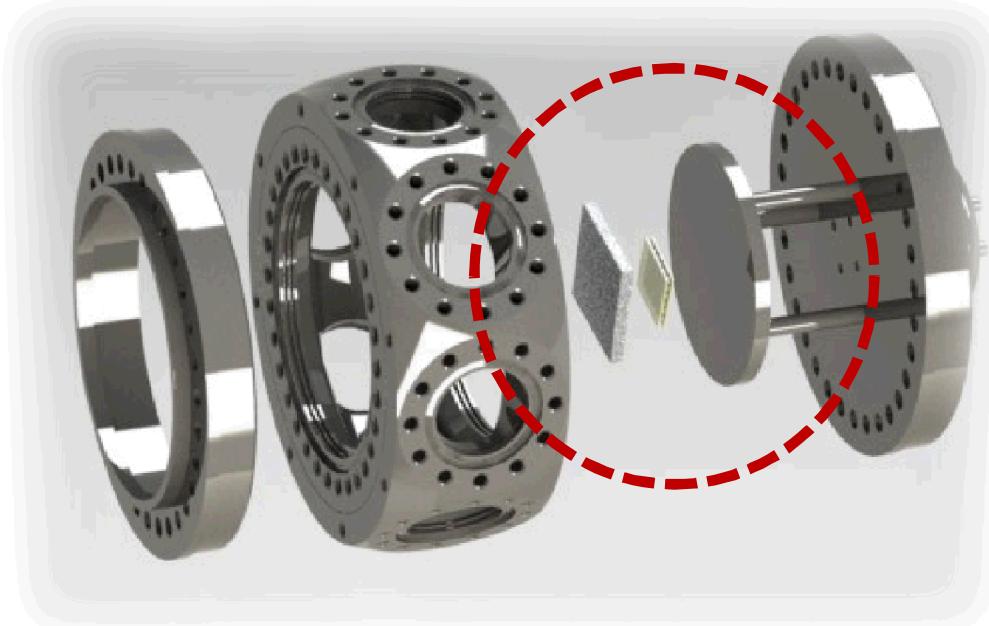
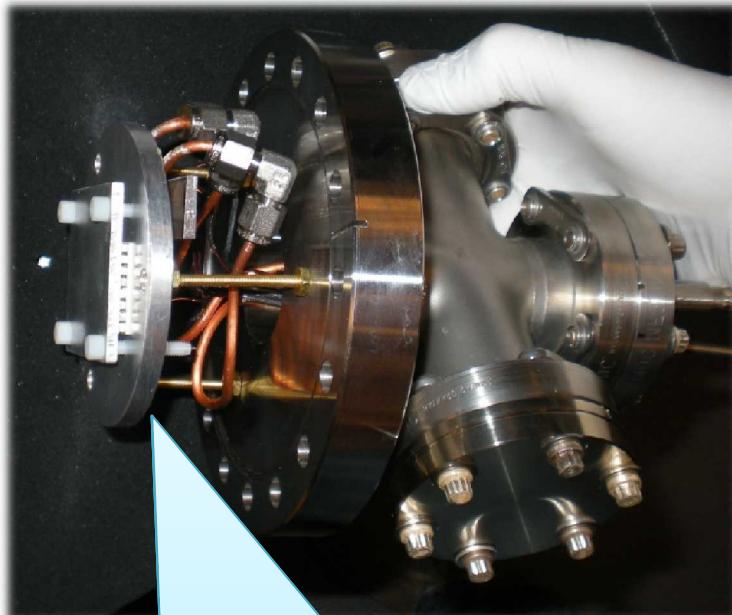
Components of the chamber

- 1-Viewing Window
- 2-Rear flange
- 3-Mounting plate





Thermal Management Design



The thermoelectric device provides easy integration into the chamber. Flat mounting plate is used for the device under test (DUT).



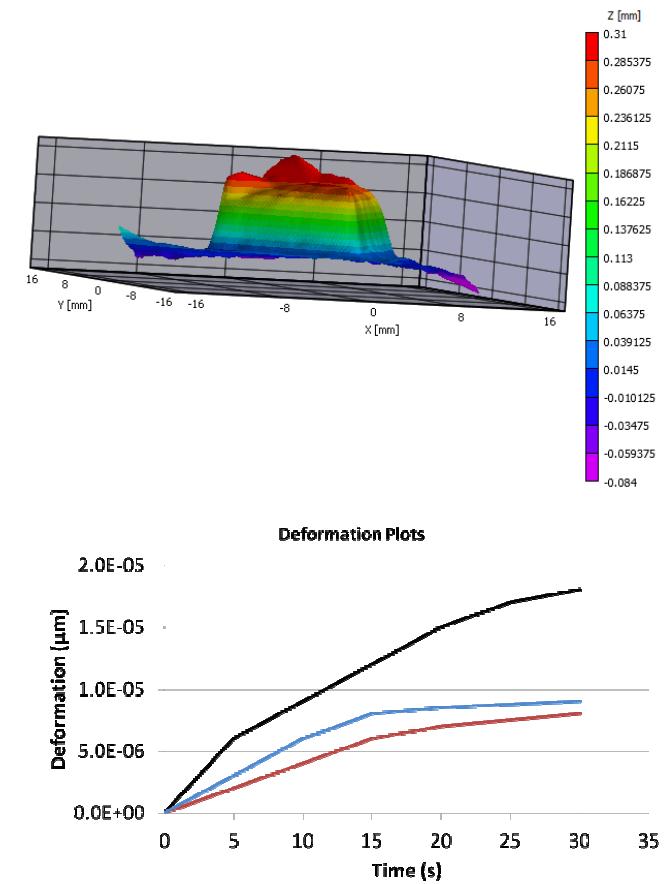
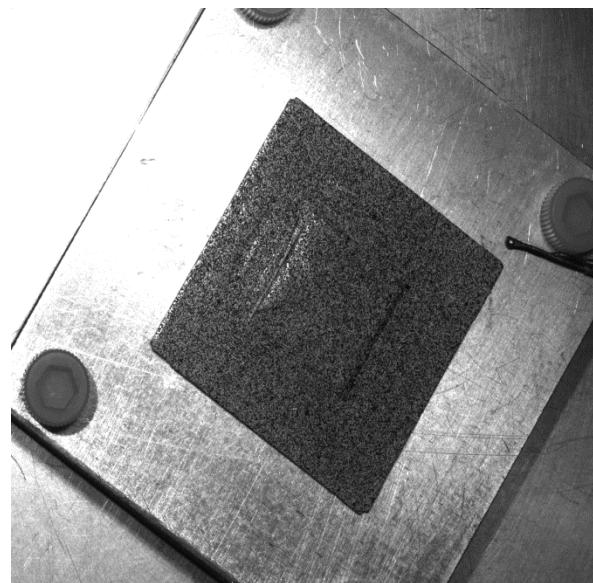
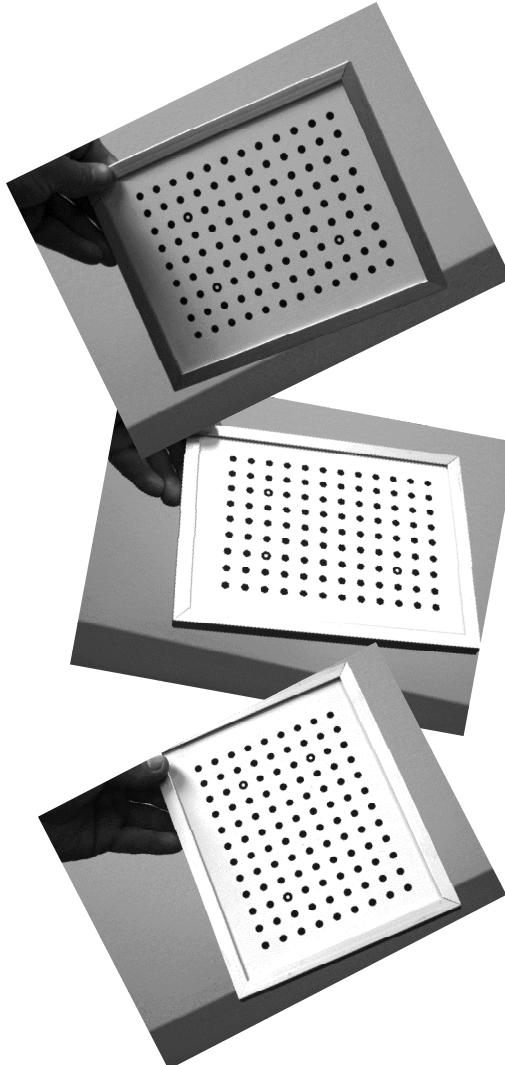
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DIC Method

Calibration → Image Acquisition → Analysis





Calibration



Translation of target grid determines intrinsic properties of imaging setup.

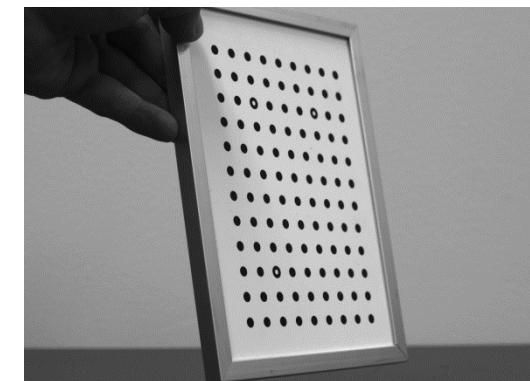
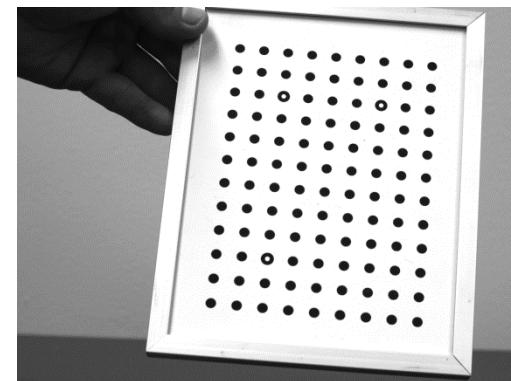
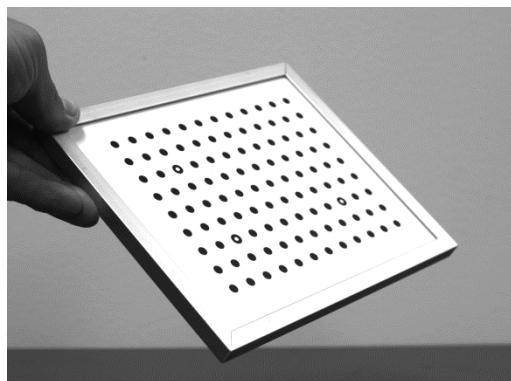
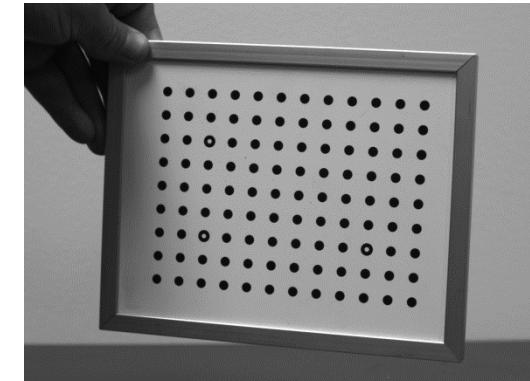
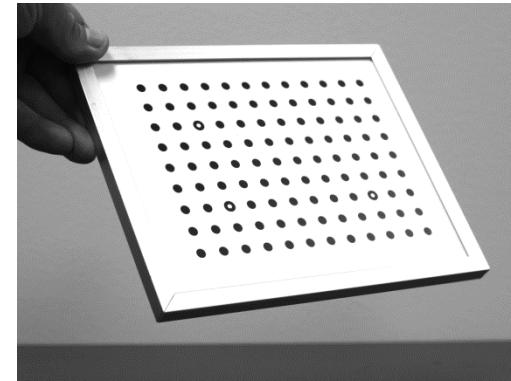
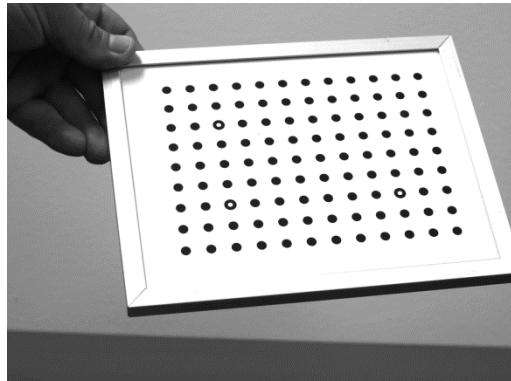
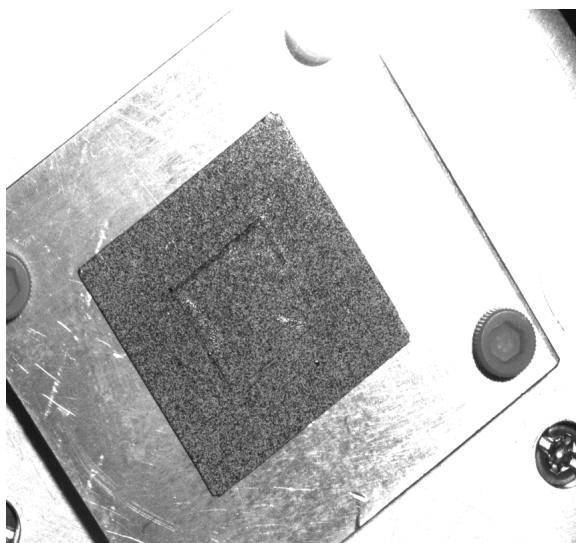


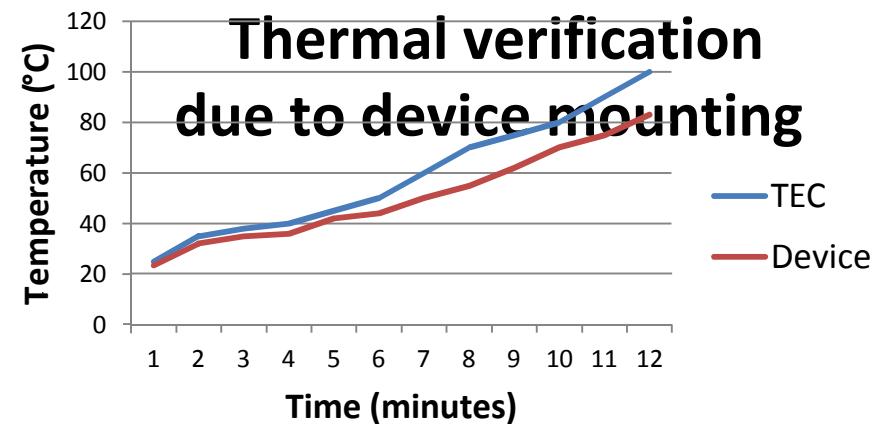
Image Acquisition

Calibration → Image Acquisition → Analysis

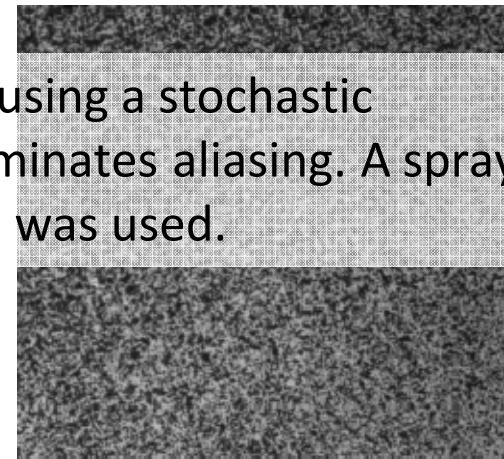
Final lighting adjustment can sometimes eliminate unwanted lighting effects and aid in calibration.



Device Temperature Profile
Thermal verification due to device mounting



Speckling using a stochastic pattern eliminates aliasing. A spray application was used.





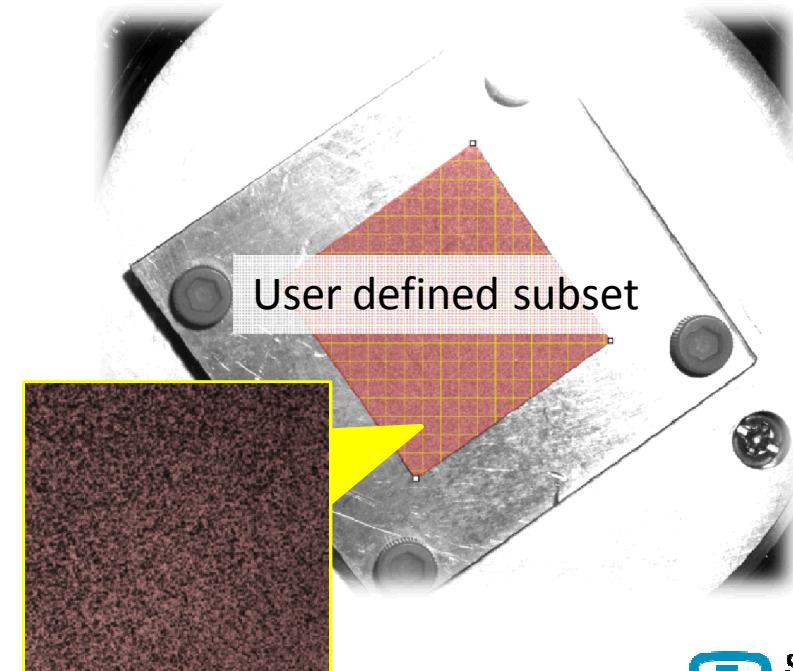
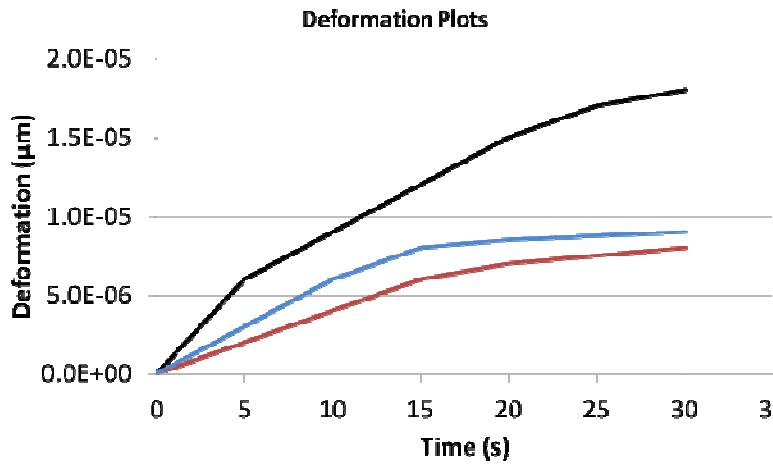
Post Process /Analysis

Calibration

Image Acquisition

Analysis

- Deformation measurement on an object surface.
- Monitors grey values “speckle pattern” for user defined subset.



Update plot ^



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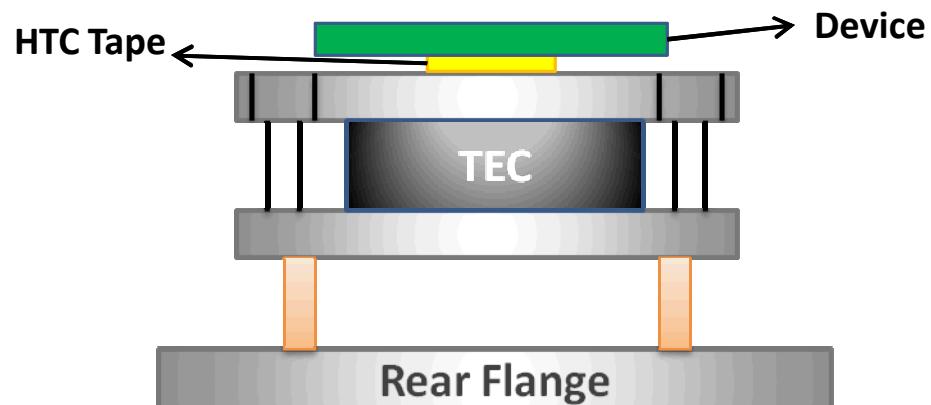
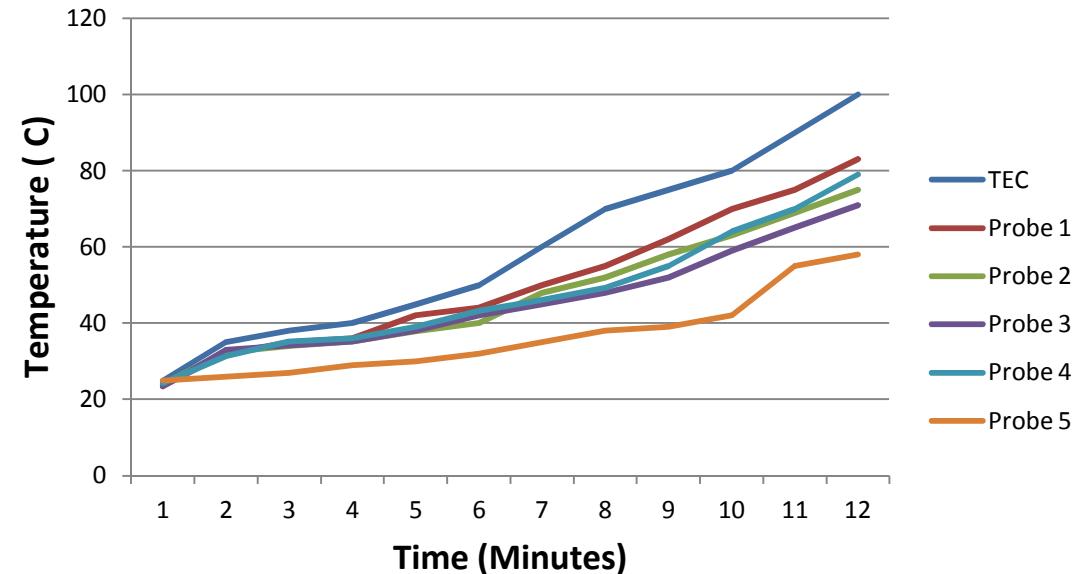


Thermal Verification



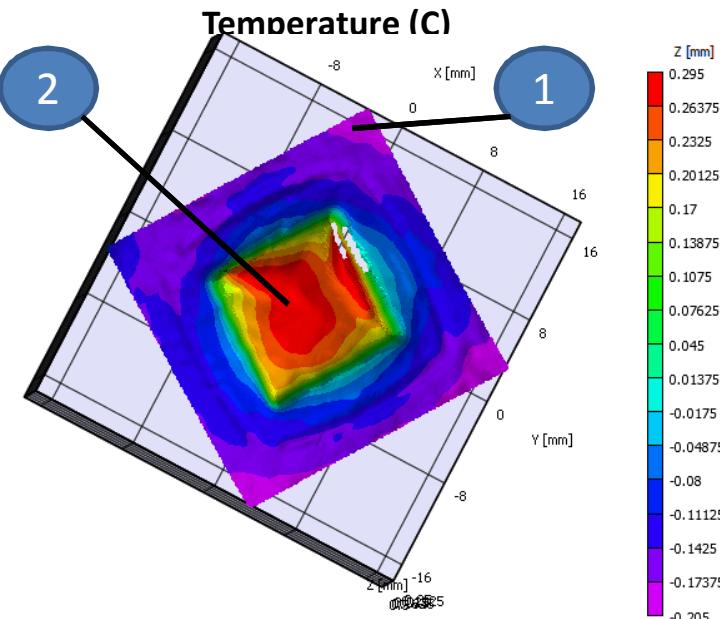
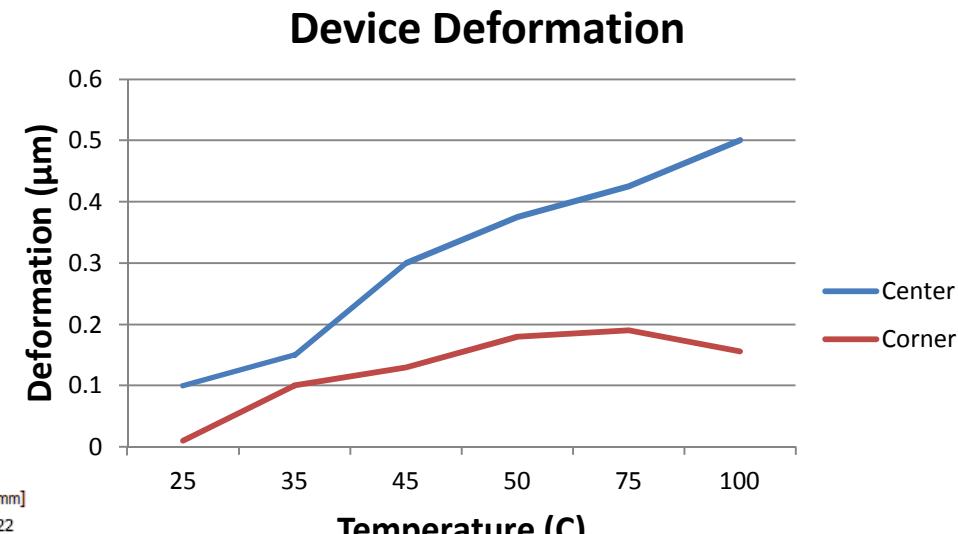
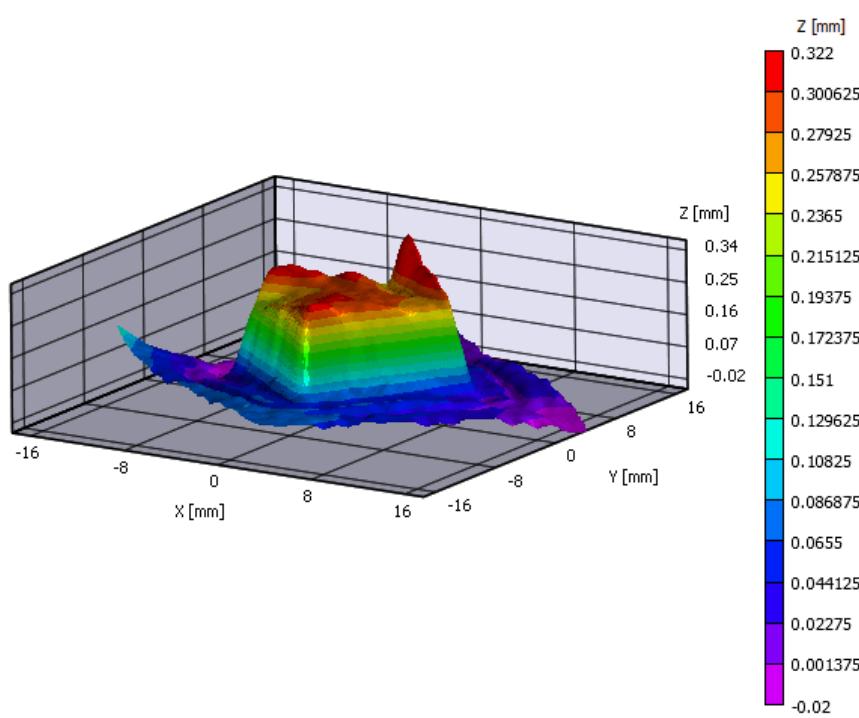
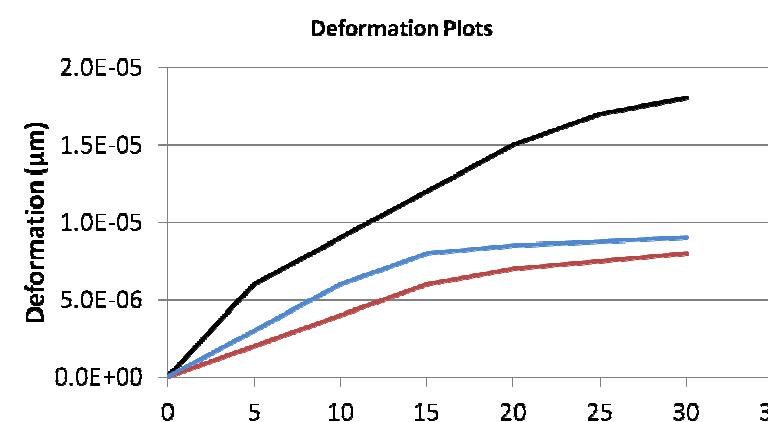
Thermocouples readings at points of interest (1-5).

Device Temperature Verification





Deformation Analysis



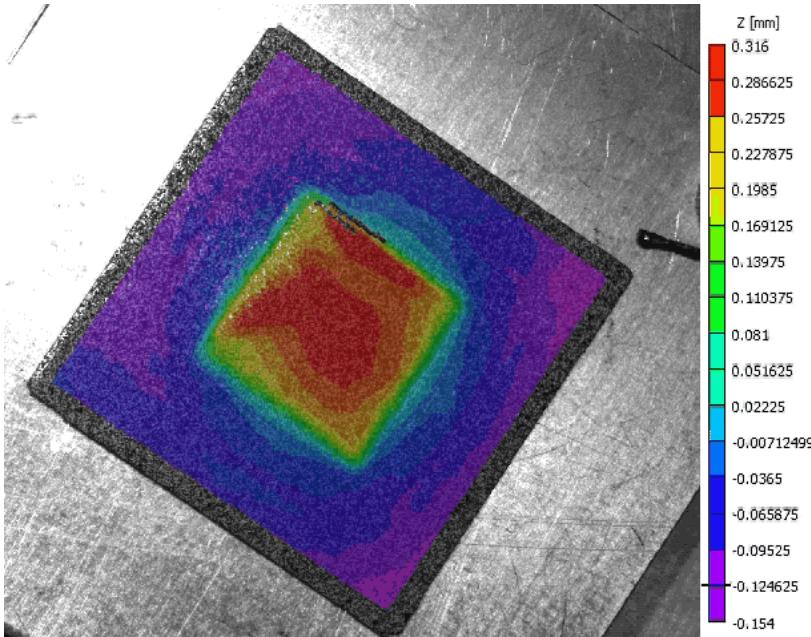
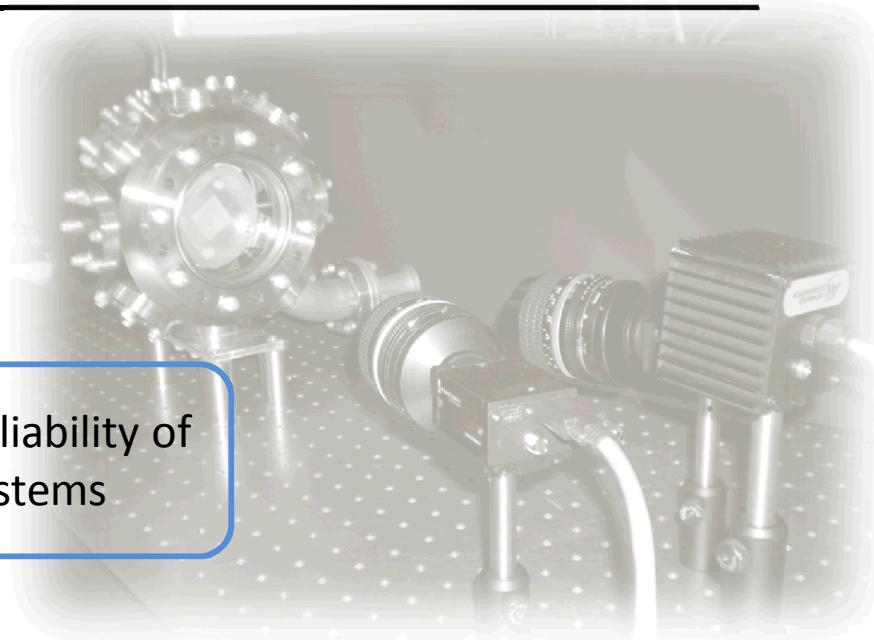
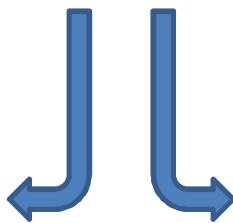


Concluding Remarks

Thermal Induced
Deformation
Characterization

Structural Model
Validation

Enhanced reliability of
microsystems



Acknowledgements

Todd Barrick, Phil Reu, Emil Kadlec